

**ON Semiconductor** **10/15/2019**

<b>Base Part</b>		<b>KA337</b>		
<b>Orderable Part</b>		<b>KA337TU</b>		<b>Total weight (mg) 2033.01</b>
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
<b>Die</b>	<b>2.81</b>	Silicon (Si)	7440-21-3	100
<b>Die Attach</b>	<b>1.111</b>	Silver (Ag)	7440-22-4	1.5
		Lead (Pb)	7439-92-1	93.5
		Tin (Sn)	7440-31-5	5
<b>Lead Frame</b>	<b>1494.949</b>	Silver (Ag)	7440-22-4	0.20067574
		Iron (Fe)	7439-89-6	0.10033787
		Copper (Cu)	7440-50-8	99.66895192
		Phosphorus (P)	7723-14-0	0.03003447
<b>Mold Compound-Black</b>	<b>518.4</b>	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	2.98996914
		Ortho Cresol Novolac Resin	29690-82-2	20.0617284
		Antimony Trioxide (Sb2O3)	1309-64-4	2.48842593
		Carbon Black (C)	1333-86-4	1
		Fused Silica (SiO2)	60676-86-0	73.45987654
<b>Plating</b>	<b>13.3</b>	Tin (Sn)	7440-31-5	100
<b>Wire Bond - Cu</b>	<b>2.44</b>	Copper (Cu)	7440-50-8	100

**Materials Disclosure Disclaimer:** Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>